# REVISION HISTORY

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<th>REVISION</th>
<th>DESCRIPTION</th>
<th>DATE</th>
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<td>INITIAL RELEASE</td>
<td>MAY 4, 2010</td>
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| B        | 1. DELETED OUTA, OUTB, OUTC.  
2. ADDED OUTPUT CONNECTOR, TITLED MOTOR.  
3. CONNECTED L2-2, L3-2 AND L4-2 TO MOTOR-1, 2 AND 3, RESPECTIVELY.  
4. DELETED PVDD, GND, +12V AND GND(GND2).  
5. ADDED POWER CONNECTOR, VIN.  
6. CONNECTED VIN-4 TO C1-1.  
7. CONNECTED VIN-2,3 TO GND.  
8. CONNECTED VIN-1 TO +12V.  
9. ADDED TESTPOINTS TO IA-FB, IB-FB, IC-FB AND I-TOTAL.  
10. ADDED 2 PIN HEADERS J2 AND J3 FOR USER POWER ACCESS.  
11. CONNECTED J2-1,2 TO +5V AND GND.  
12. CONNECTED J3-1,2 TO +3.3V AND GND.  
14. ADDED 3 PIN HEADER, JP3, LABELED TACH/SPEED INPUT.  
15. CONNECTED JP3-1,2,3 TO +3.3V, J1-7 AND GND, RESPECTIVELY.  
16. RENAMED S1 TO RSTA.  
17. SWAPPED U1-29 AND U1-30.  
18. ADDED 40 PIN HEADER, J5 AND CONNECTED PINS TO ACTIVE PINS OF J1.  
19. ADDED SWITCHES, S1 AND S2 TO U1-76 AND U1-78.  
20. COPIED DAC1 CIRCUIT, CALLED DAC3, AND CONNECTED TO J1-28.  
21. CHANGED R24-R27 TO 33.0K OHMS.  
22. CHANGED R28-R35, R56-R61 TO 1.00K OHMS.  
23. CHANGED R48, R49, R54 AND R55 TO 49.9K OHMS.  
24. ADDED ISOLATION CIRCUITS.  
25. ADDED 12V CONNECTOR, J9.  
26. CHANGED C4 TO 22UF/100V.  
27. CHANGED C5 AND C6 TO 100V. | MARCH 23, 2011 | RK |
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